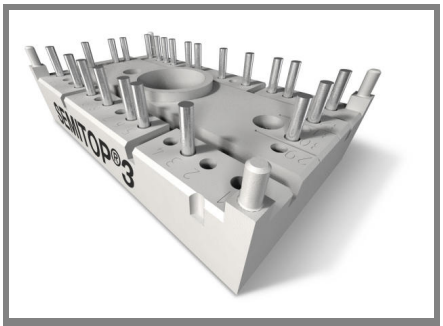
SK 70 DH



SEMITOP® 3

Half Controlled Bridge Rectifier

SK 70 DH

Preliminary Data

Features

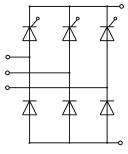
- Compact design
- One screw mounting
- Heat transfer and insolation through direct copper bonded aluminium oxide ceramic (DBC)
- Glass passived thyristor chips
- Up to 1600V reverse voltage
- UL recognized, file no. E 63 532

Typical Applications*

- Soft starters
- Light control
- Temperature control
- Motor control

V_{RSM} V	V_{RRM}, V_{DRM} V	I_D = 68 A (full conduction) (T_s = 80 °C)
900	800	SK 70 DH 08
1300	1200	SK 70 DH 12
1700	1600	SK 70 DH 16

Symbol	Conditions	Values	Units
I_D	T_s = 80 °C	68	A
I_{FSM} / I_{TSM}	T_{vj} = 25 °C; 10 ms	370	A
	T_{vj} = 125 °C; 10 ms	270	A
i²t	T_{vj} = 25 °C; 10 ms	685	A²s
	T_{vj} = 125 °C; 10 ms	365	A²s
V_T	T_{vj} = 25 °C; 75A	max. 1,9	V
$V_{T(TO)}$	T_{vj} = 125 °C;	max. 1	V
r_T	T_{vj} = 125 °C	max. 10	mΩ
I_{DD}; I_{RD}	T_{vj} = 125 °C; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}	max. 10	mA
t_{gd}	T_{vj} = 25 °C; I_G = 1 A; di_G/dt = 1 A/µs	1	µs
t_{gr}	V_D = 0,67 · V_{DRM}	2	µs
$(dv/dt)_{cr}$	T_{vj} = 125 °C	max. 1000	V/µs
$(di/dt)_{cr}$	T_{vj} = 125 °C; f = 50...60 Hz	max. 50	A/µs
t_q	T_{vj} = 125 °C; typ.	120	µs
I_H	T_{vj} = 25 °C; typ. / max.	80 / 150	mA
I_L	T_{vj} = 25 °C; R_G = 33 Ω	150 / 300	mA
V_{GT}	T_{vj} = 25 °C; d.c.	min. 2	V
I_{GT}	T_{vj} = 25 °C; d.c.	min. 100	mA
V_{GD}	T_{vj} = 125 °C; d.c.	max. 0,25	V
I_{GD}	T_{vj} = 125 °C; d.c.	max. 3	mA
Rth(j-s)	Per thyristor	1,2	K/W
	Per diode	1,7	K/W
T_{solder}	Terminals, 10s	260	°C
T_{vj}	Diodes	-40...+150	°C
T_{vj}			°C
T_{stg}		-40...+125	°C
T_{vj}	Thyristors	-40...+125	°C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3000 (2500)	V
M_s	Mounting torque to heatsink	2,5	Nm
m	weight	30	g
Case	SEMITOP® 3	T 40	



DH

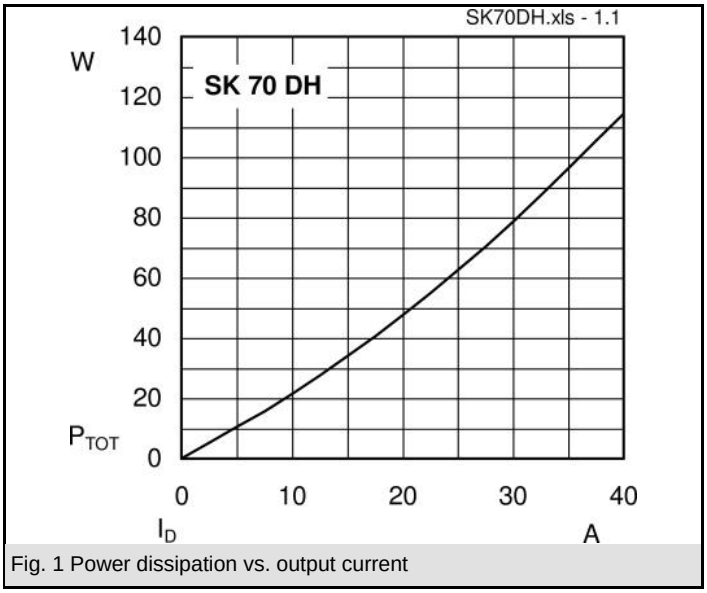


Fig. 1 Power dissipation vs. output current

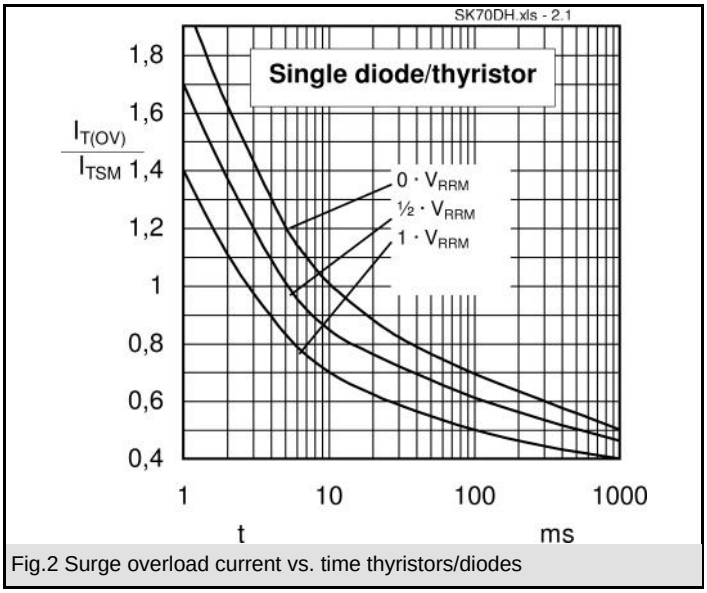


Fig.2 Surge overload current vs. time thyristors/diodes

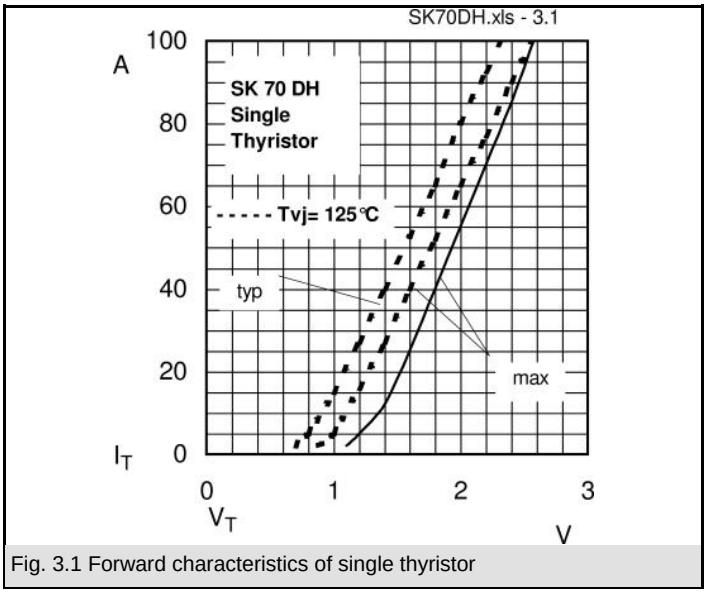


Fig. 3.1 Forward characteristics of single thyristor

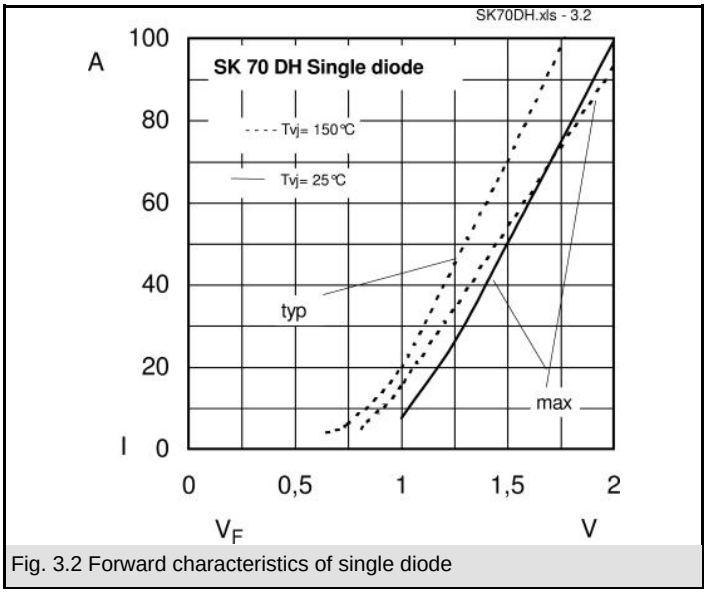


Fig. 3.2 Forward characteristics of single diode

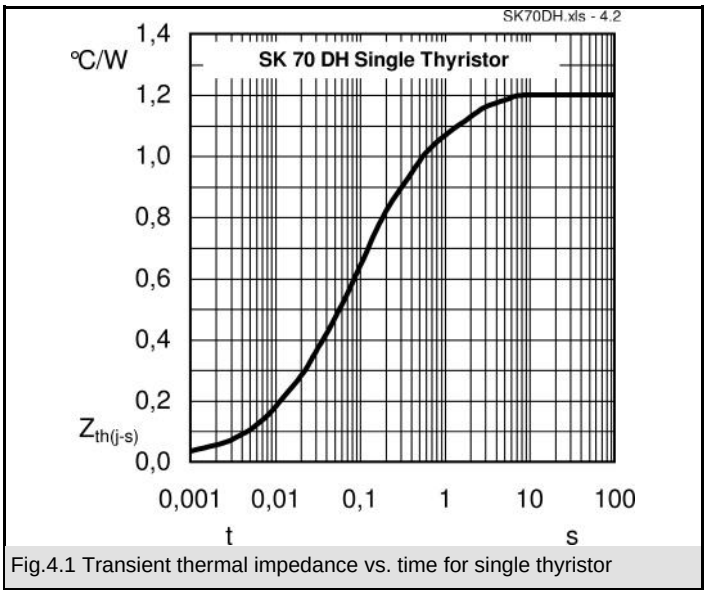


Fig.4.1 Transient thermal impedance vs. time for single thyristor

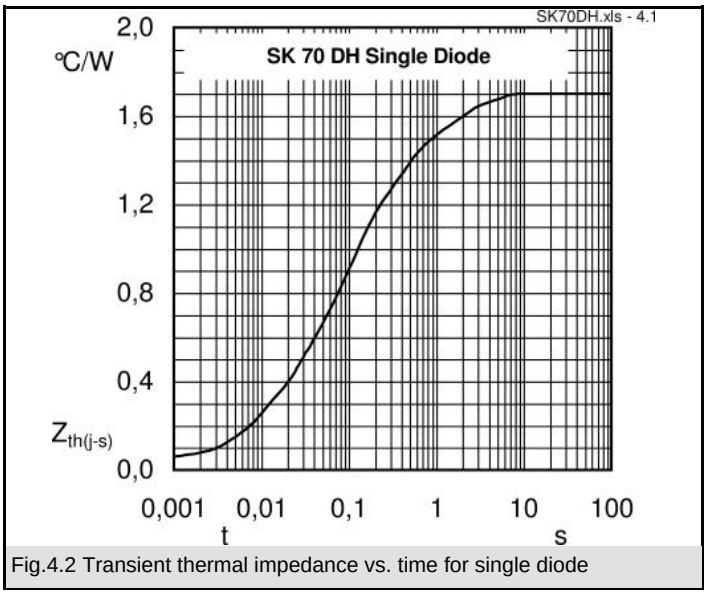


Fig.4.2 Transient thermal impedance vs. time for single diode

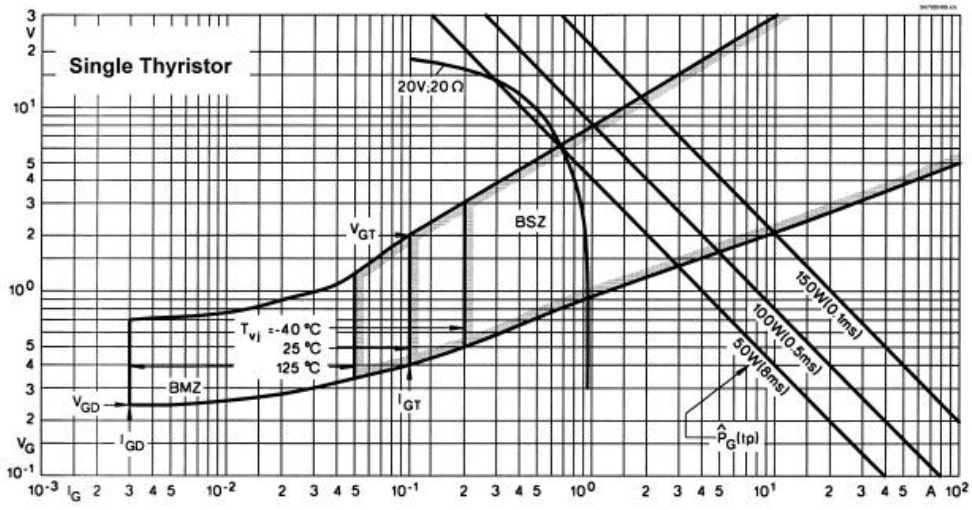
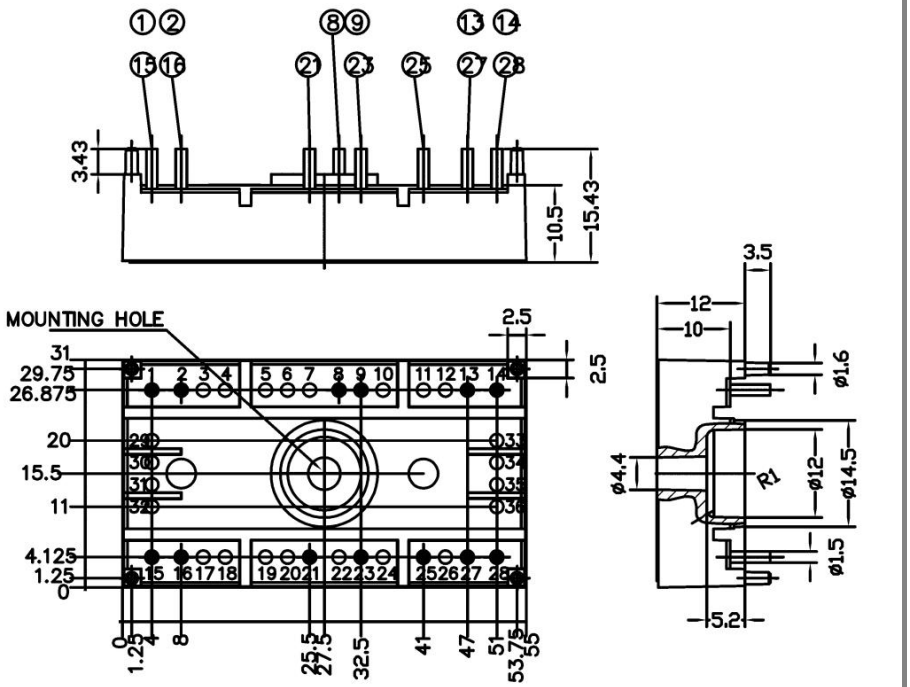
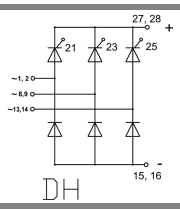


Fig. 5 Gate trigger characteristics

Dimensions in mm



Case T40 (Suggested hole diameter for plastic mounting pins and solder pins in the PCB: 2mm)



Case T40 DH

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

